

03-10-2005



To the Honorable Commissioner of

Attached original documents or copy thereof.

02/25/05

1. Name of conveying party(ies):

Arup Bhattacharyya (December 10, 2004)

102956882

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Address: 8000 South Federal Way
Boise, Idaho 83716

Additional name(s) of conveying party(ies) attached? Yes No

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: See Above

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: February 25, 2005

- A. Patent Application No(s). Unknown
- B. Patent No(s).

Title: SCALABLE HIGH DENSITY NON-VOLATILE MEMORY CELLS USING MULTI-MECHANISM CARRIER TRANSPORT

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Kenneth W. Bolvin
Address: Leffert Jay & Polglaze, P.A.
P.O. Box 581009
Minneapolis, MN 55458-1009

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR §3.41): \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to Deposit account number: 501373

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is an original or a true copy of the original document.

Kenneth W. Bolvin Reg. No. 34,125
Name of Person Signing

Kenneth W. Bolvin
Signature

2/25/05
Date

Total number of pages including cover sheet, attachments, and document(s): 3

Mail documents to be recorded with required cover sheet information to:

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

03/09/2005 6TON11 00000064 11066900
01 FC:8021 40.00 OP

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ASSIGNMENT

WHEREAS, I, Arup Bhattacharyya, residing at 18 Glenwood Drive, Essex Junction, Vermont, 05452 made certain new and useful inventions and improvements for which I executed an application for Letters Patent of the United States herewith, and which is entitled SCALABLE HIGH DENSITY NON-VOLATILE MEMORY CELLS USING MULTI-MECHANISM CARRIER TRANSPORT.

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, Boise, Idaho, 83716, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, I have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, I do hereby agree that I and my respective executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to me relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore I covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by me.

